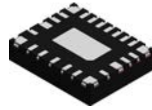

PACKAGE OUTLINE

VQFN-FCRLF - 1.05 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

B 4.1 3.9 A

PIN 1 INDEX AREA

5.1 4.9

0.1 MIN

(0.1)

SECTION A-A
TYPICAL

1.05 0.95

C

SEATING PLANE

0.01 0.00

0.08 C

1.4±0.1

PKG ℄

EXPOSED THERMAL PAD

4X 1.6

2X 0.775

8

(0.035) TYP

10X 0.45 0.35

0.1Ⓜ C A B

0.05Ⓜ C

(0.1) TYP

(0.2) TYP

2X 0.65 0.45

7

12

2X 0.725

0.75

A A

SYMM ℄

1.5

25

2.4±0.1

3

22X 0.7 0.5

2X 0.625

8X 0.5

2X 0.6

18X 0.3 0.2

1

20

0.1Ⓜ C A B

0.05Ⓜ C

24

PIN 1 ID (45° X 0.2)

2X 0.775

2X 0.05

2X 0.525

2X 0.575

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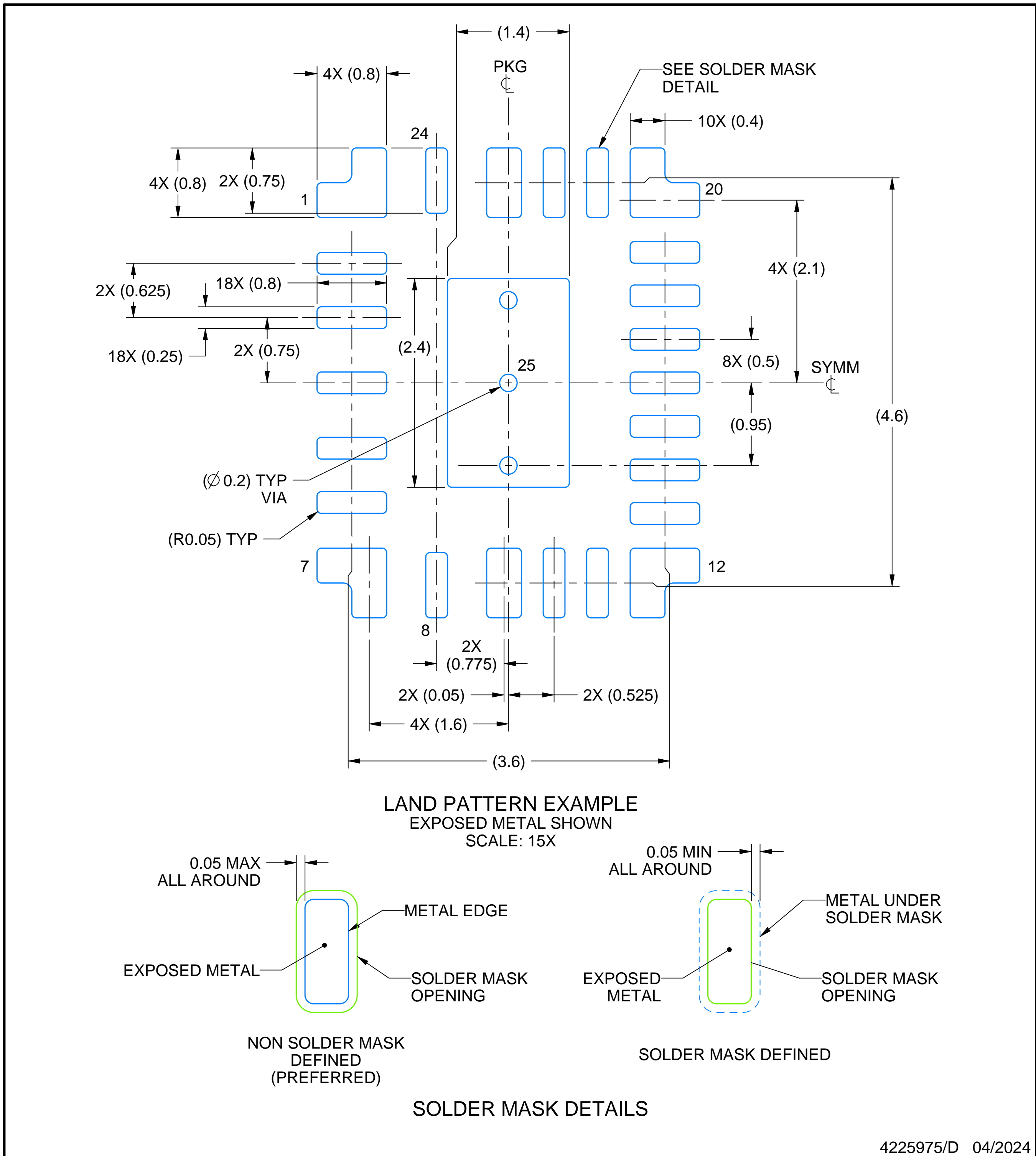
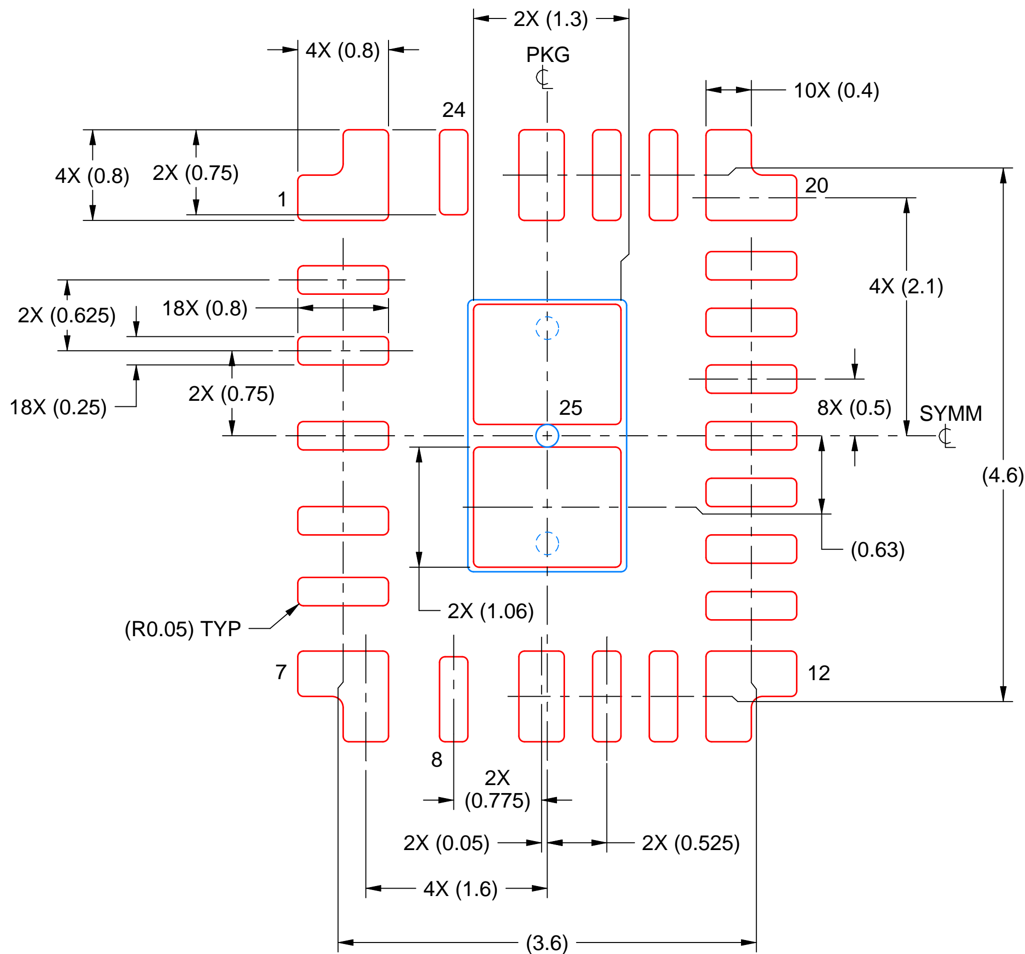
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 15X

EXPOSED PAD 23:
79% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.